

## Excellent Integrated System Limited

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[Samsung Electro-Mechanics America, Inc.](#)  
[CL10B105KA8NNND](#)

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**SAMSUNG  
ELECTRO-MECHANICS**



## SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL10B105KA8NNND**
- Description : **CAP, 1 $\mu$ F, 25V,  $\pm$ 10%, X7R, 0603**

### A. Samsung Part Number

CL   10   B   105   K   A   8   N   N   N   D  
 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.6 $\pm$ 0.1 mm	W: 0.8 $\pm$ 0.1 mm
③ Dielectric	X7R	⑧ Inner electrode	Ni
④ Capacitance	1 $\mu$ F	Termination	Cu
⑤ Capacitance tolerance	$\pm$ 10 %	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	25 V	⑨ Product	Normal
⑦ Thickness	0.8 $\pm$ 0.1 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Cardboard Type, 13" reel

### B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz $\pm$ 10%      1.0 $\pm$ 0.2Vrms
Tan $\delta$ (DF)	0.1 max.	
Insulation Resistance	10,000Mohm or 100Mohm $\cdot\mu$ F Whichever is Smaller	Rated Voltage      60~120 sec.
Appearance	No abnormal exterior appearance	Microscope ( $\times$ 10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	X7R (From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change should be within $\pm$ 15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10 $\pm$ 1 sec.
Bending Strength	Capacitance change : within $\pm$ 12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 $\pm$ 5 $^{\circ}$ C, 3 $\pm$ 0.3sec. (preheating : 80~120 $^{\circ}$ C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within $\pm$ 7.5% Tan $\delta$ , IR : initial spec.	Solder pot : 270 $\pm$ 5 $^{\circ}$ C, 10 $\pm$ 1sec.

	Performance	Test condition
<b>Vibration Test</b>	Capacitance change : within $\pm 5\%$ Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Moisture Resistance</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.125 max IR : 12.5M $\Omega \cdot \mu F$ or Over	With rated voltage 40 $\pm 2^\circ C$ , 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.125 max IR : 25M $\Omega \cdot \mu F$ or Over	With 150% of the rated voltage Max. operating temperature  1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 7.5\%$ Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ C$ $\rightarrow$ Max. operating temperature $\rightarrow 25^\circ C$  5 cycle test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature : 260+0/-5 $^\circ C$ , 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.